

APPENDIX

1. (Amended) An apparatus, comprising a semiconductor polishing device having a first surface defining at least [one] two non-intersecting fluid retaining grooves at least a portion of which is oriented at an angle relative to a radial line originating at a center of the semiconductor polishing device, wherein the non-intersecting fluid retaining grooves [is] are adapted to flow a fluid inwardly toward a center portion of the semiconductor polishing device.
3. (Amended) The apparatus of claim 1, wherein [the] a depth of at least one of the non-intersecting fluid retaining grooves changes along a length of the at least one non-intersecting fluid retaining groove.
4. (Amended) The apparatus of claim 1, wherein at least one of the non-intersecting fluid retaining grooves has a first portion and a second portion having a same direction of curvature and defining a tangent point to the radial line.
5. (Amended) The apparatus of claim 1, wherein the non-intersecting fluid retaining grooves [is] are oriented in a direction of rotation moving at an increasing radius from a first end of the grooves to a second end of the grooves.
6. (Amended) The apparatus of claim 1, wherein the non-intersecting fluid retaining grooves [is] are oriented in a direction of rotation moving at an increasing radius along a length of the non-intersecting fluid retaining grooves.
7. (Amended) The apparatus of claim 1, wherein the non-intersecting fluid retaining grooves [is] are selected from arcuate grooves, linear grooves, and any combination thereof.
8. (Amended) The apparatus of claim 1, wherein the non-intersecting fluid retaining grooves extend[s] from the center portion of the semiconductor polishing

device to an edge of the semiconductor polishing device and wherein no point of the non-intersecting fluid retaining groove is tangent to the radial line.